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Response Under 37 C.F.R. 1.116 (After Final)
Expedited Procedure Examining Group 2827

Attorney Docket: KAM/133/PC/US

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Application No. 09/786,597
Applicant(s): Kenichi Hirahara et al.
Filing Date: February 28, 2001
Title: Through Hole Conduction Structure of Flexible
Multilayer Circuit Board and Forming Method
Thereof
Group/Art Unit 2827
Examiner: Tuan T. DINH

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Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

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Response to Final Office Action Under 37 C.F.R. 1.116

Sir:

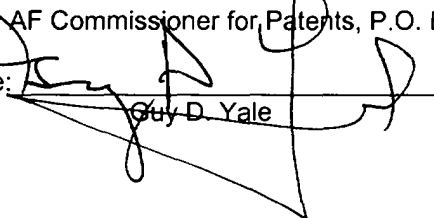
This amendment is being made under 37 C.F.R. §1.116. In response to the Office Action of July 7, 2003 please amend the above-identified application as follows:

Amendments to the Claims are reflected in the listing of claims which begins on page 2 of this paper.

Mailing Certificate

I hereby certify that this correspondence is being deposited on the date given below with the United States Post Office Service as First Class mail in an envelope addressed to:
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Guy D. Yale

Reg. No.: 29,125 Date: September 9, 2003